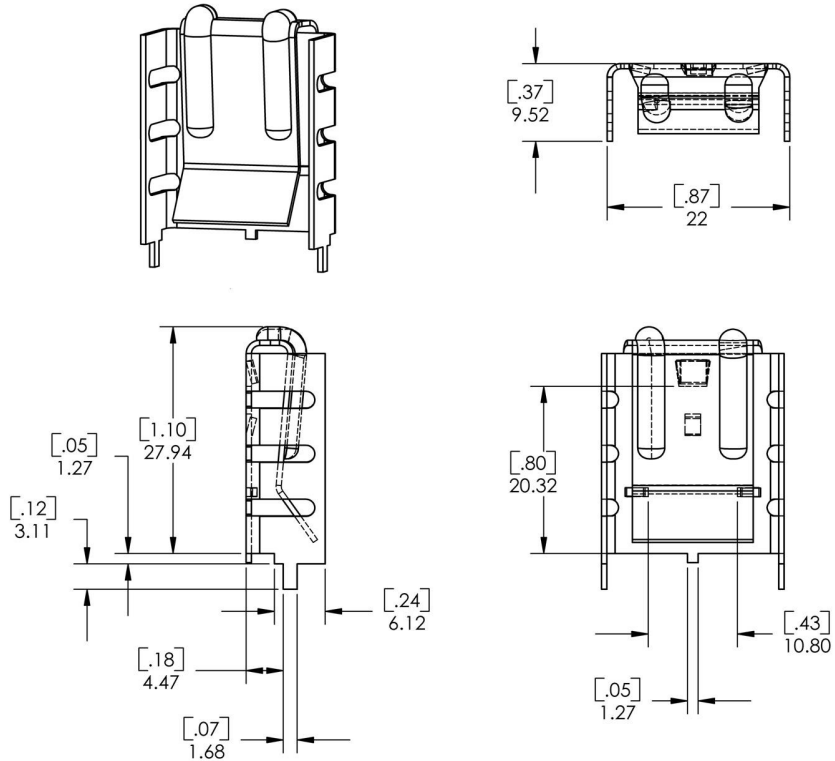
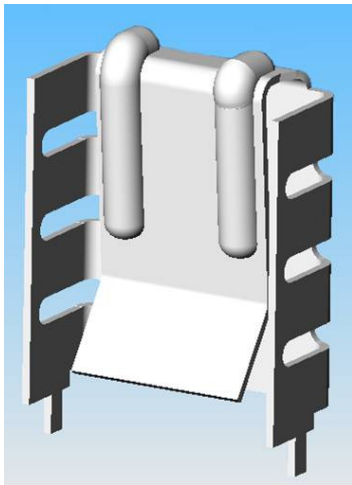


Board Level Heat Sinks



ThermaFlo

P/N: 833702T00000



PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 9.5 x 22.0 x 28.0mm
- Material: Copper, 0.6mm thick
- Type: Stamped
- Finish: Tin Plate
- PCB Mounting: Solderable Tabs
- IC Mounting: Integrated Spring
- Package: Bulk

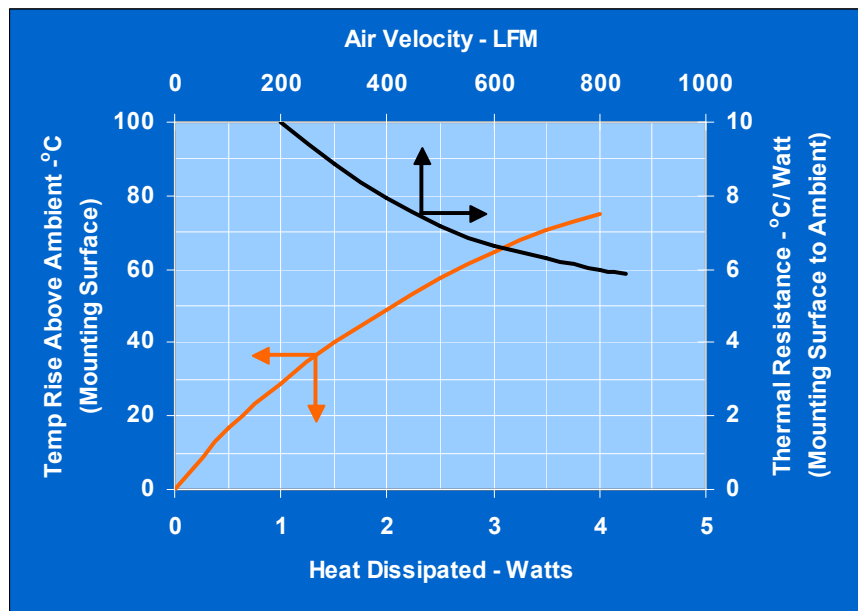
FEATURES & BENEFITS

- No Hardware Device Attachment
- Constant Spring Force Tension
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Tabs, Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220

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